

DF6A6.8FUT1

Quad Array for ESD Protection

This quad voltage suppressor is designed for applications requiring transient overvoltage protection capability. It is intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment, and other applications. Its quad junction common anode design protects four separate lines using only one package. These devices are ideal for situations where board space is at a premium.

Specification Features

- SC-88 Package Allows Four Separate Unidirectional Configurations
- Low Leakage < 1 μ A @ 5 Volt
- Breakdown Voltage: 6.4 – 7.2 Volt @ 5 mA
- Low Capacitance (40 pF typical)
- ESD Protection Meeting 61000-4-2 Level 4 and 16 kV Human Body Model
- Pb-Free Package is Available

Mechanical Characteristics

- Void Free, Transfer-Molded, Thermosetting Plastic Case
- Corrosion Resistant Finish, Easily Solderable
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Power Dissipation @ 8 x 20 μ s (Note 1)	P_{pk}	75	Watts
Steady State Power Dissipation (Note 2)	P_D	385	mW
Thermal Resistance – Junction-to-Ambient Derate Above 25°C	$R_{\theta JA}$	328 3.0	$^\circ\text{C/W}$ mW/ $^\circ\text{C}$
Maximum Junction Temperature	T_{Jmax}	150	$^\circ\text{C}$
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$
ESD Discharge MIL STD 883C – Method 3015-6 IEC61000-4-2, Air Discharge IEC61000-4-2, Contact Discharge	V_{PP}	16 16 8	kV
Lead Solder Temperature (10 seconds duration)	T_L	260	$^\circ\text{C}$

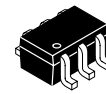
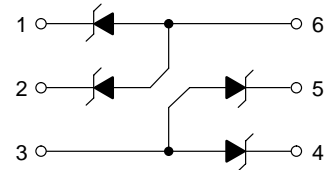
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Per Waveform Figure 1
2. Mounted on FR-5 Board = 1.0 X 0.75 X 0.062 in.



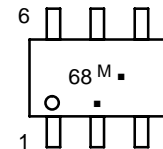
ON Semiconductor®

<http://onsemi.com>



SC-88
CASE 419B-02

MARKING DIAGRAM



68 = Specific Device Code

M = Date Code

▪ = Pb-Free Package

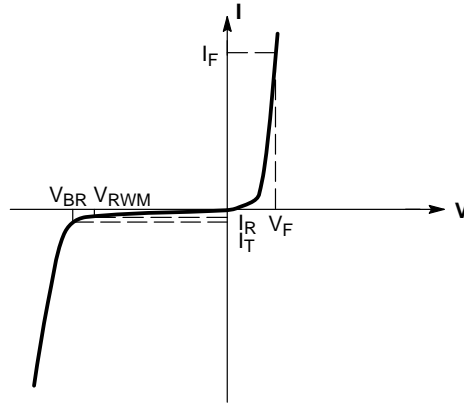
(Note: Microdot may be in either location.)

ORDERING INFORMATION

Device	Package	Shipping†
DF6A6.8FUT1	SC-88	3000/Tape & Reel
DF6A6.8FUT1G	SC-88 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DF6A6.8FUT1



V-I Curve

ELECTRICAL CHARACTERISTICS

Device	Device Marking	Breakdown Voltage V_{BR} @ 5 mA (Volts)			Leakage Current I_{RM} @ $V_{RWM} = 5$ V	Typical Capacitance @ 0 V Bias	Max V_F @ $I_F = 10$ mA	Max Z_Z @ 5 mA	Max Z_{ZK} @ 0.5 mA
		Min	Nom	Max	(μ A)	(pF)	(V)	(Ω)	(Ω)
DF6A6.8FUT1	68	6.4	6.8	7.2	1.0	40	1.25	30	300

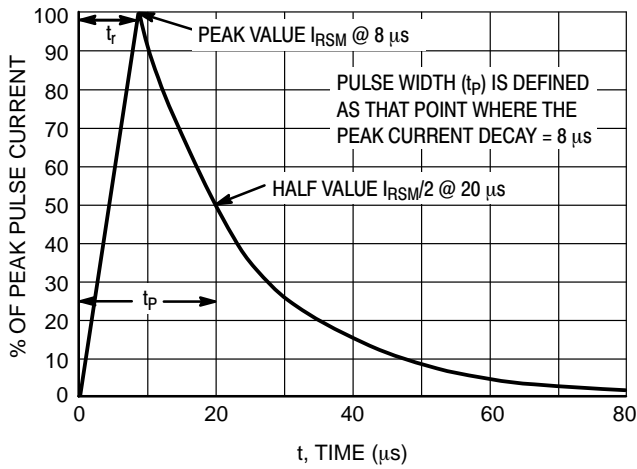


Figure 1. $8 \times 20 \mu s$ Pulse Waveform

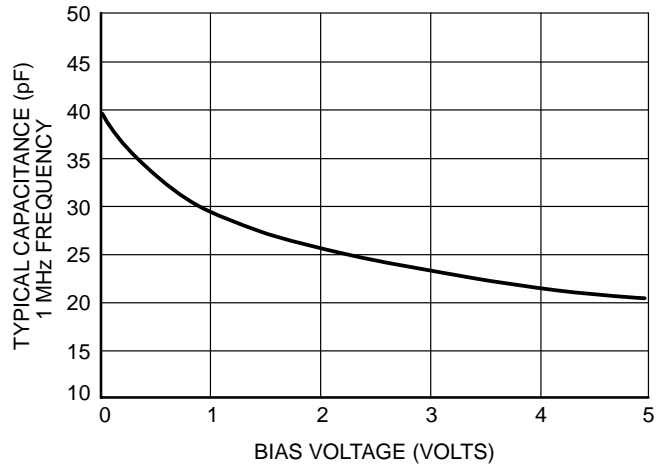


Figure 2. Capacitance

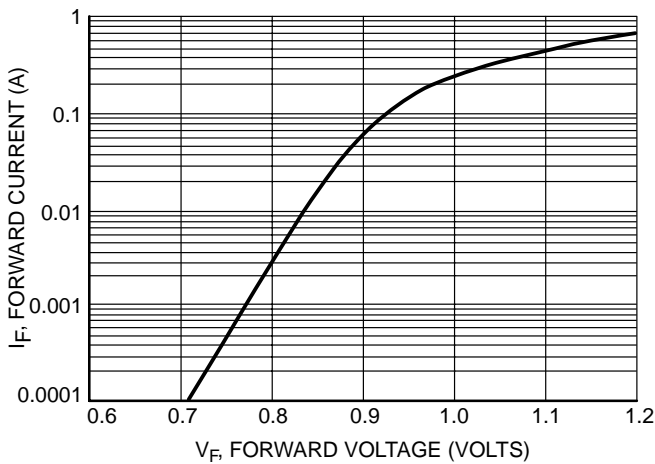


Figure 3. Forward Voltage

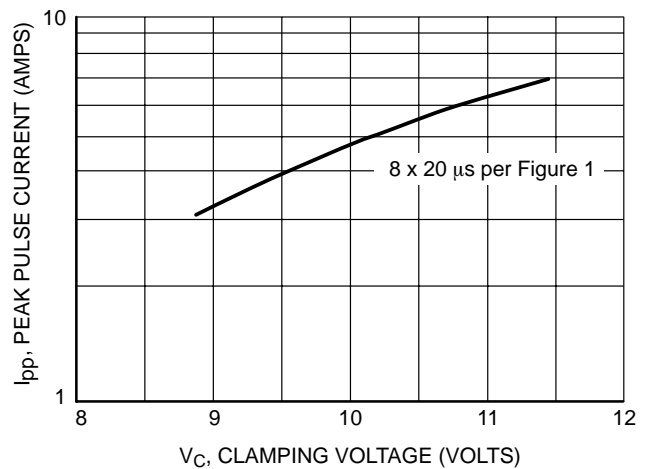
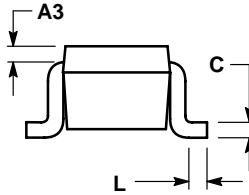
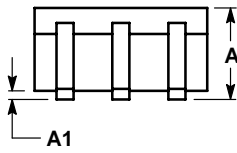
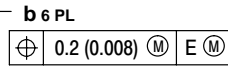
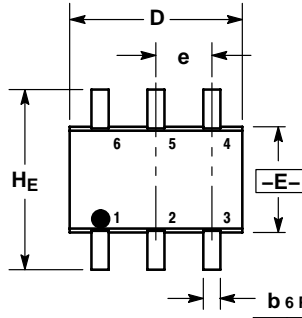


Figure 4. Clamping Voltage versus Peak Pulse Current

DF6A6.8FUT1

PACKAGE DIMENSIONS

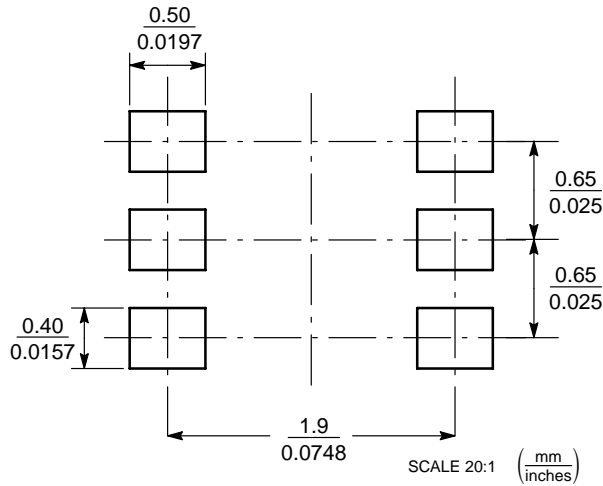
SC-88/SC70-6/SOT-363
CASE 419B-02
ISSUE V



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.20 REF			0.008 REF		
b	0.10	0.21	0.30	0.004	0.008	0.012
C	0.10	0.14	0.25	0.004	0.005	0.010
D	1.80	2.00	2.20	0.070	0.078	0.086
E	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65 BSC			0.026 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	2.00	2.10	2.20	0.078	0.082	0.086

SOLDERING FOOTPRINT*



SC-88/SC70-6/SOT-363

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DF6A6.8FUT1

ON Semiconductor and  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
P.O. Box 61312, Phoenix, Arizona 85082-1312 USA
Phone: 480-829-7710 or 800-344-3860 Toll Free USA/Canada
Fax: 480-829-7709 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center
2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051
Phone: 81-3-5773-3850

ON Semiconductor Website: <http://onsemi.com>

Order Literature: <http://www.onsemi.com/litorder>

For additional information, please contact your
local Sales Representative.